



Material Content Data Sheet



Sales Product Name				IPZ40N04S5-3R1		Issued		9. January 2019	
MA#				MA001710580					
Package				PG-TSDSON-8-33		Weight*		36.50 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	0.566	1.55	1.55	15503	15503	
leadframe	inorganic material	phosphorus	7723-14-0	0.003	0.01		85		
	non noble metal	zinc	7440-66-6	0.012	0.03		341		
	non noble metal	iron	7439-89-6	0.249	0.68		6816		
wire	non noble metal	copper	7440-50-8	10.102	27.68	28.40	276751	283993	
	noble metal	gold	7440-57-5	0.031	0.09	0.09	853	853	
	encapsulation	organic material	carbon black	1333-86-4	0.036	0.10		992	
encapsulation	plastics	epoxy resin	-	1.865	5.11		51091		
	inorganic material	silicondioxide	60676-86-0	16.205	44.39	49.60	443946	496029	
leadfinish	non noble metal	tin	7440-31-5	0.400	1.10	1.10	10965	10965	
plating	noble metal	silver	7440-22-4	0.086	0.23	0.23	2346	2346	
solder	non noble metal	tin	7440-31-5	0.016	0.04		442		
	noble metal	silver	7440-22-4	0.020	0.06		553		
	non noble metal	lead	7439-92-1	0.771	2.11	2.21	21126	22121	
heatspreader	inorganic material	phosphorus	7723-14-0	0.001	0.00		16		
	non noble metal	zinc	7440-66-6	0.002	0.01		64		
	non noble metal	iron	7439-89-6	0.047	0.13		1287		
	non noble metal	copper	7440-50-8	1.908	5.23	5.37	52260	53627	
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.001	0.00		34		
	non noble metal	zinc	7440-66-6	0.005	0.01		137		
	non noble metal	iron	7439-89-6	0.100	0.28		2750		
	non noble metal	copper	7440-50-8	4.075	11.16	11.45	111642	114563	
*deviation	< 10%		Sum in total:			100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com